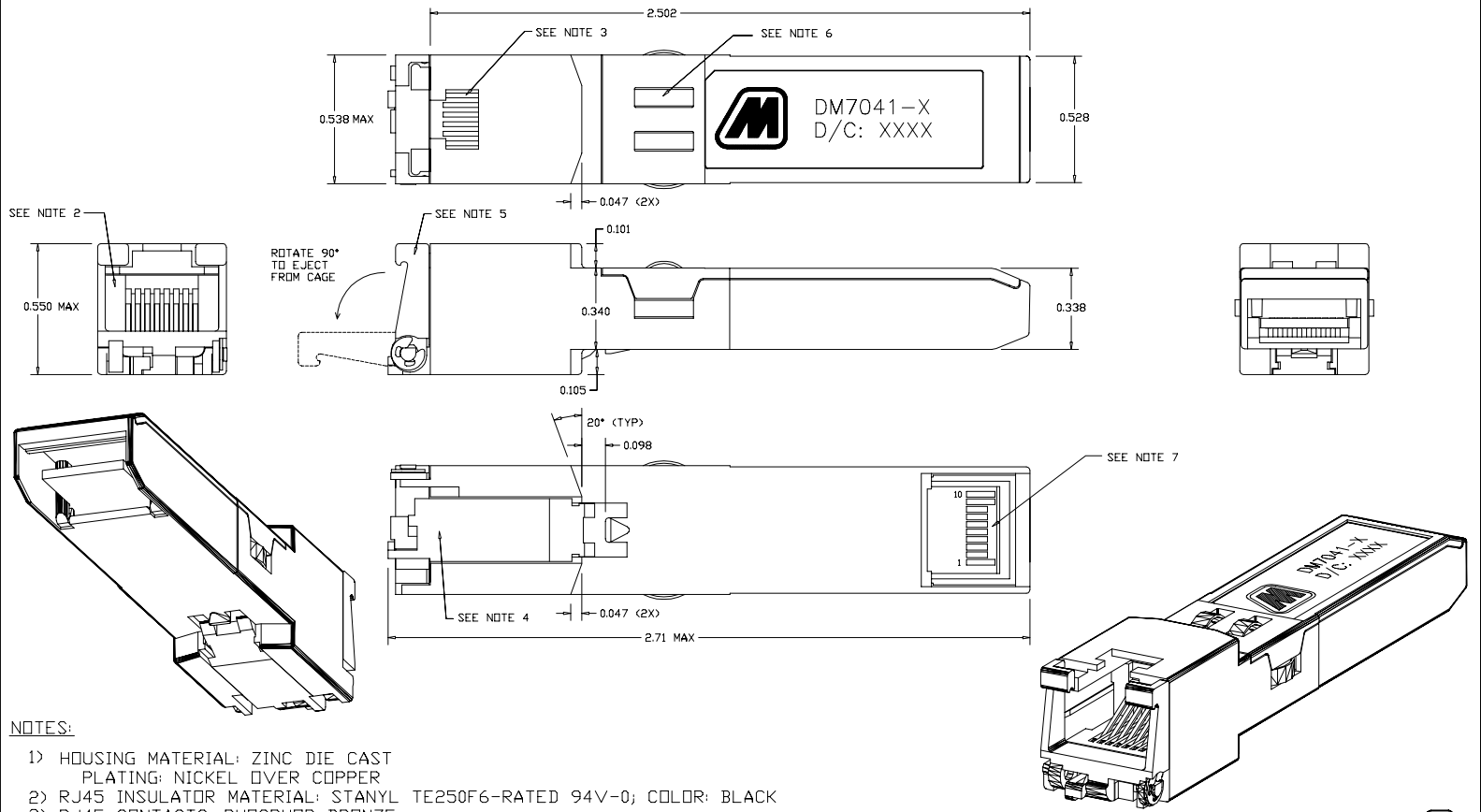


REVISION AND CHANGE EFFECTIVITY DATE				
LTR.	ECN	DESCRIPTION	DATE	APP'D.
N	EC1509	CHANGED TO IMPROVED SLIDER MECHANISM	06/16/08	AP



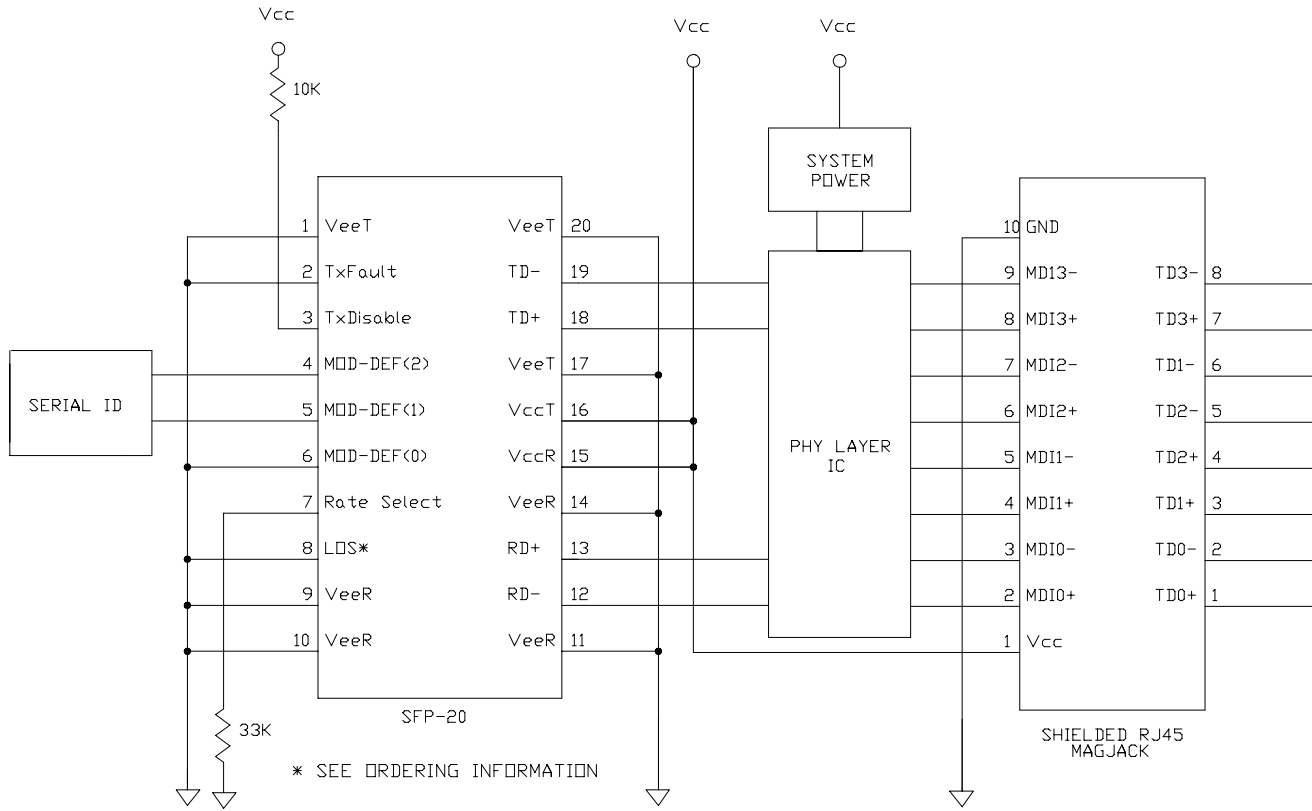
**NOTES:**

- 1) HOUSING MATERIAL: ZINC DIE CAST  
PLATING: NICKEL OVER COPPER
- 2) RJ45 INSULATOR MATERIAL: STANYL TE250F6-RATED 94V-0; COLOR: BLACK
- 3) RJ45 CONTACTS: PHOSPHOR BRONZE  
PLATING: 50µin MIN. HARD GOLD ON CONTACT AREA,  
TIN/LEAD ON SOLDER AREA
- 4) EJECTOR ACTUATOR: ZINC DIE CAST  
PLATING: NICKEL OVER COPPER
- 5) BAIL LATCH: MIM STEEL WITH GOLD FLASH OVER Cu/Ni PLATING
- 6) GROUNDING TABS: BERYLLIUM COPPER  
PLATING: NICKEL
- 7) PCB-.039" THICK; 30µin. MIN GOLD PLATING OVER  
50µin. MIN NICKEL ON CONTACT AREA

DO NOT SCALE DRAWING.		EXPERIMENTAL NO:		DIVISION ASSIGNED: <b>dataMate Division</b>	
TOLERANCE UNLESS OTHERWISE SPECIFIED		MATERIAL: SEE NOTES		DRAWN BY: A. PIRILLIS DATE: 2/3/03	
METRIC INCHES		FINISH:		CHECKED BY: T. LEGITIND 2/3/03	
± FRACS: DEC: XX ± .010 ANGLES ± .005				ENGR. APPROVAL: B. SKEPNEK 2/3/03	
± TOOLING DWG □ PART DWG □ BREAK SHARP EDGES REMOVE ALL BURRS				APPROVED BY: J. DALY 2/3/03	
THE INFORMATION DISCLOSED IN THIS DOCUMENT IS PROPRIETARY TO METHODE ELECTRONICS, INC. AND MAY NOT BE USED FOR MANUFACTURE OR ANY OTHER PURPOSE WITHOUT THE WRITTEN CONSENT OF METHODE. DETAILS SUBJECT TO CHANGE AS THEY MAY CHANGE WITH RESPECT TO PRODUCT IMPROVEMENT.		PART NO. CLASSIFICATION:		TITLE: SFP TO RJ45 MODULE WITH BAIL LATCH	
SIZE: C	CODE IDENT.	DWG. NUMBER: DM7041-X	Rev. H	SCALE: SH1.1 OF 2	



REVISION AND CHANGE EFFECTIVITY DATE				
LTR.	ECN	DESCRIPTION	DATE	APP'D.
N	EC1509	CHANGED TO IMPROVED SLIDER MECHANISM	06/16/06	AP



**ORDERING INFORMATION**

DM7041-X  
 — BLANK- LOS CONNECTED TO GND (NORMAL OPERATION)  
 — L- LOS CONNECTED TO LINK1000 TO INDICATE LINK ON CABLE SIDE

\* SEE ORDERING INFORMATION

PREVIOUS REVISIONS			
A	DATE	DESCRIPTION	APP'D.
A	06/09/03	MODIFIED LAYER	AP
B	06/14/03	ADDED LOS OPTION	AP
C	9/7/03	ADDED STEP AND INCREASED THICKNESS	RWS
D	1/20/04	UPDATED SFP GOLD PLATING SPEC	RWS
E	07/26/04	CHANGED MATERIAL ON BAIL AND GROUNDING TAB	AP
F	1/16/06	CORRECTED PIN ASSIGNMENT ON PL45	RWS
G	2/27/06	MATERIALS CHANGE	RWS

DO NOT SCALE DRAWING.

EXPERIMENTAL NO:		DIVISION ASSIGNED: <b>dataMate Division</b>	
TOLERANCE UNLESS OTHERWISE SPECIFIED		DRAWN BY: <b>A. PIRILLIS</b> DATE: 2/3/03	
MATERIAL: SEE NOTES		CHECKED BY: <b>T. LEGITTIMO</b> DATE: 2/3/03	
METRIC INCHES		ENGR. APPROVAL: <b>B. SKEPNEK</b> DATE: 2/3/03	
± FRACTION ± DEC. XX ± .010		APPROVED BY: <b>J. DALY</b> DATE: 2/3/03	
± ANGLES ±		PART NO. CLASSIFICATION:	
TOOLING DWG □		TITLE: <b>SFP TO RJ45 MODULE WITH BAIL LATCH</b>	
PART DWG □		SIZE: <b>C</b> CODE IDENT. DWG. NUMBER: <b>DM7041-X</b> Rev. <b>H</b>	
BREAK SHARP EDGES REMOVE ALL BURRS		SCALE:	
<small>THE INFORMATION DISCLOSED IN THIS DOCUMENT IS PROPRIETARY TO METHODE ELECTRONICS, INC. AND MAY NOT BE USED FOR MANUFACTURE OR ANY OTHER PURPOSE WITHOUT THE WRITTEN CONSENT OF METHODE. DETAILS SUBJECT TO CHANGE AS THEY MAY CHANGE WITH RESPECT TO PRODUCT IMPROVEMENT.</small>			

